

Conductor paste for semi-fixed resister application

TR-2964

Main features:

Pb free conductor paste with excellent solder leach resistance

Typical Fired Properties: Ag/Pd/Pt

Metal Ratio	wt%	78/13/9
Recommended Firing Temperature	°C	850
Fired Thickness	μm	11±3
Resistivity	mΩ/□ at 10μm	≦45
Solder acceptance	%	≧90
Solder leach resistance	Cycles	*≧4
Adhesion strength	Initial 150°C 1000H N/2mm□	30 30
Viscosity	Pa*s	200±50
Thinner		TMS-8

Attention: These pastes and powders are materials for industrial use only. Refer to appropriate MSDS and statement of caution.

Notice: Values in each data are not specified, just representative values.

Instruction in Using Thickfilm Paste Products

1. Storage...

Tight a lid after using and store in dark and cold place. Shelf life depends on the product but usually speaking 6 months is maximum to use comfortably. Stirring with palette-knife or spatula is recommended before using.

2. Substrate...

Properties are normally applicable on 96% alumina substrates (standard IC grade)

There is the possibility that similar results can not be achieved with a substrate of different manufacturer. Bend, surface roughness or cleanliness of substrate effectively influences paste performances. If other substrate will be used with, please ask us about compatibility.

3. Viscosity and Adjustment...

Brookfield viscometer type HBT with spindle SC4-14 and chamber 6R is mainly used in the catalogue. Viscosity and rheology have much effect on screen printability, severe control is recommended. Viscosity measurement is recommended to use comfortably after long storage period. Recommended solvents for each product is needed to adjust viscosity, Mix paste and proper amount of solvent gently and make them uniform. Proper size of pallet-knife or spatula is recommended for the mixing operation

4. Screen Printing...

C.W. Price and Presco Printer and mesh number between 200 and 400 of stainless screen are mainly used in TTK. Controlling emulsion thickness, stencil, print pressure, snap-off distance, squeegee speed and angle are important to get correct thickness and fine line printability.

5. Leveling and Drying...

Leveling time for 5~10min. in room temperature is recommended to avoid remaining mesh-mark of screen.

Drying about 120°C for 10~15min. is recommended after leveling..

6. Firing...

Belt furnaces are recommended for firing, some cautions are indicated as follows,

*Halogen solvent has effect on performance of fired film, pay attention not to enter vapors into furnace.

*Set up the air entrance for proper gotten fresh air in flow.

*Oil free dry pump with air filter needed to supply air into furnace

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